

Patent Abstracts of Japan

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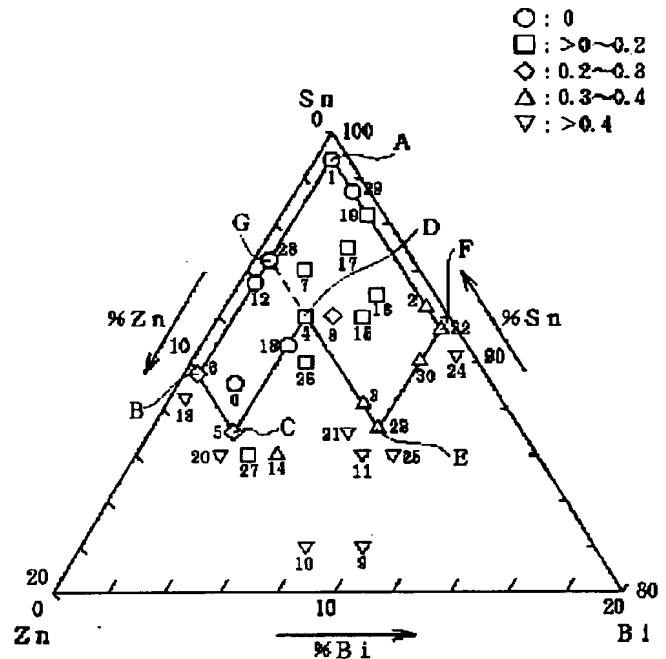
APPLICATION DATE : 02-02-96
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APPLICANT : SONY CORP;

INVENTOR : HANIYU KAZUTAKA;

INT.CL. : B23K 35/26 C22C 13/00

TITLE : SOLDERING MATERIAL



ABSTRACT : PROBLEM TO BE SOLVED: To provide a soldering material without a fear of environmental pollution, having sufficient mechanical strength, and approximately showing the same melting temp. property as a conventional tin-lead soldering material.

SOLUTION: This soldering material is composed of, by wt., 0.5-10% zinc, 0.5-8% bismuth and substantially the balance tin (however, the chemical composition consisting of, by wt., >5% to <10% zinc, >3% to <8% bismuth and substantially the balance tin is excluded). Namely, the soldering material is specified to be the chemical composition within the area enclosed with line segments AB, BC, CD, DE, EF and FA.

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